L	Hits	Search Text	DB	Time stamp
Number				
1	887920	(substrate carrier board pcb ((printed	USPAT;	2004/08/25
		wiring cirucit) adj4 board)) with (via	US-PGPUB;	09:36
		through hole opening open)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	887920		USPAT;	2004/08/25
		wiring circuit) adj4 board)) with (via	US-PGPUB;	09:36
		through hole opening open)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	2576778	,	USPAT;	2004/08/25
•		(integrated adj circuit)	US-PGPUB;	09:37
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
4	345363	The same of the sa	USPAT;	2004/08/25
		radiating radiated metal slug)	US-PGPUB;	09:45
			EPO; JPO;	İ
			DERWENT;	1
_	6377		IBM_TDB	
5	63//	//= m======== m==== pem //p=====	USPAT;	2004/08/25
		wiring circuit) adj4 board)) with (via through hole opening open)) same	US-PGPUB;	09:45
		(semiconductor chip die ic dice	EPO; JPO;	
		(integrated adj circuit)) same (heat with	DERWENT;	
		(sink spreader radiate radiating radiated	IBM_TDB	1
		metal slug))		
6	84318		USPAT;	2004/08/25
-	3.310	board pcb ((printed wiring circuit) adj4	US-PGPUB;	09:46
		board)) with (via through hole opening	EPO; JPO;	05.40
		open)) same (semiconductor chip die ic	DERWENT;	
		dice (integrated adj circuit)) same (heat	IBM TDB	
		with (sink spreader radiate radiating		
		radiated metal slug)))		
7	942	(bumps ball) same (((substrate carrier	USPAT;	2004/08/25
		board pcb ((printed wiring circuit) adj4	US-PGPUB;	09:46
		board)) with (via through hole opening	EPO; JPO;	
		open)) same (semiconductor chip die ic	DERWENT;	
		dice (integrated adj circuit)) same (heat	IBM_TDB	
		with (sink spreader radiate radiating	_	
	<u> </u>	radiated metal slug)))		